### **General Description**

The SJC68N058 uses advanced trench technology to provide excellent R<sub>DS(ON)</sub>, low gate charge and operation with gate voltages as low as 10V. This device is suitable for use as a wide variety of applications.

#### **Features**

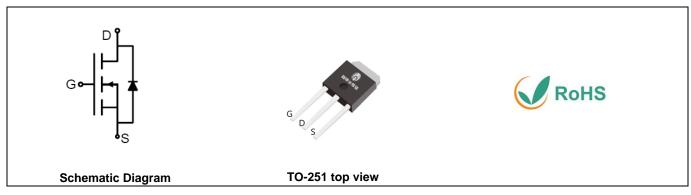
- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handing capability
- Lead free product is acquired

### **Application**

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

### **Key Performance Parametes**

Parameter	Value	Unit
V <sub>DS</sub>	68	V
R <sub>DS(ON)_TYP</sub>	5.6	mΩ
I <sub>D</sub>	82	A
Q <sub>G</sub>	90	nC



### **Package Marking and Ordering Information**

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJC68N058	SJC68N058	TO-251	Tube	\	\	4000 Pcs

Table 1. Absolute Maximum Ratings (T<sub>C</sub>=25℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V <sub>DS</sub>	Drain-Source Voltage (V <sub>GS</sub> =0V)	68	V
Vgs	Gate-Source Voltage (V <sub>DS</sub> =0V)	±20	V
ı	Drain Current-Continuous(Tc=25°C)	82	А
I <sub>D</sub>	Drain Current-Continuous(Tc=100°C)	52	А
I <sub>DM</sub> (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	328	А
D-	Maximum Power Dissipation(T <sub>C</sub> =25°C)	94	W
P <sub>D</sub>	Maximum Power Dissipation(T <sub>C</sub> =100°C)	38	W
Eas	Avalanche energy (Note 2)	441	mJ
T <sub>J</sub> , T <sub>STG</sub>	Operating Junction and Storage Temperature Range	-55 To 150	℃

#### Table 2. Thermal Characteristic

Symbol	Parameter		Max	Unit
R JC	Thermal Resistance, Junction-to-Case		1.33	°C/W



Table 3. Electrical Characteristics ( $T_J=25^{\circ}C$  unless otherwise noted)

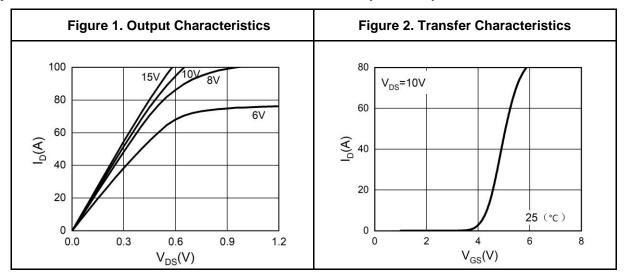
Symbol	Parameter	Conditions	Min	Тур	Max	Unit	
On/Off States							
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	68			V	
	7 0 1 1/1 5 1 0 1	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V T <sub>J</sub> =25°C			500	nA	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =68V, V <sub>GS</sub> =0V T <sub>J</sub> =125°C			500	nA	
Igss	Gate-Body Leakage Current	V <sub>GS</sub> =±10V, V <sub>DS</sub> =0V			±100	nA	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2		4	V	
<b>G</b> FS	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =20A		36.5		S	
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =20A T <sub>J</sub> =25°C		5.8	7	mΩ	
Dynamic Charac	cteristics					•	
Ciss	Input Capacitance			4724		pF	
Coss	Output Capacitance	V <sub>DS</sub> =30V,V <sub>GS</sub> =0V, f=1.0MHz		225		pF	
C <sub>rss</sub>	Reverse Transfer Capacitance			207		pF	
Rg	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1.0MHz		0.73		Ω	
Switching Parar	neters						
t <sub>d(on)</sub>	Turn-on Delay Time			9		nS	
tr	Turn-on Rise Time	$V_{GS}=10V$ , $V_{DS}=30V$ , $R_{L}=1.5\Omega$ , $R_{GEN}=6\Omega$		7		nS	
t <sub>d(off)</sub>	Turn-Off Delay Time	KL=1.352, KGEN=052		40		nS	
t <sub>f</sub>	Turn-Off Fall Time			15		nS	
Qg	Total Gate Charge			90		nC	
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> =10V, V <sub>DS</sub> =30V, I <sub>D</sub> =20A		10		nC	
$Q_{gd}$	Gate-Drain Charge			18		nC	
Source-Drain Diode Characteristics							
I <sub>SD</sub>	Source-Drain Current (Body Diode)				82	А	
V <sub>SD</sub>	Forward on Voltage (Note 3)	V <sub>GS</sub> =0V, I <sub>S</sub> =20A			0.99	V	
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =20A, dI/dt=100A/ s		33		ns	
Qrr	Reverse Recovery Charge	Ir=20A, dI/dt=100A/ s		46		nC	

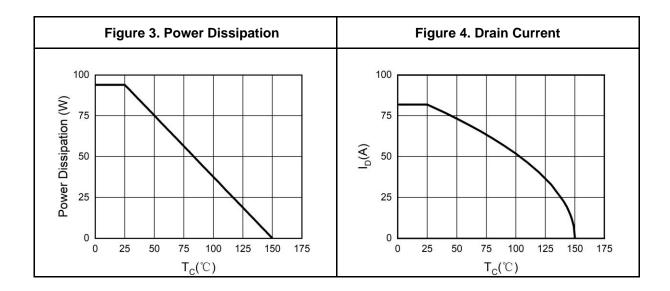
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

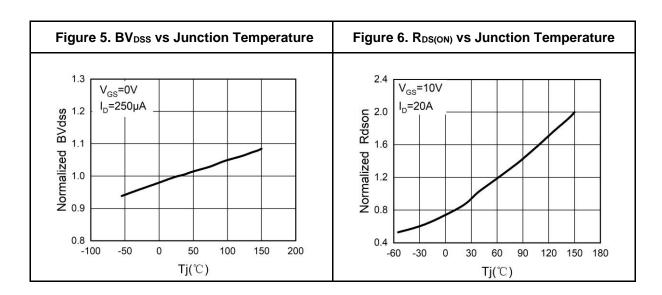
Notes 2.Eas condition: TJ=25  $^{\circ}$ C,VDD=40V,VG=10V, Rg=25 $\Omega$ , L=0.5mH.

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.

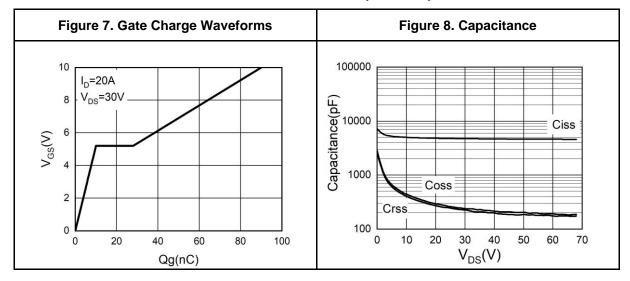
# **Typical Electrical And Thermal Characteristics (Curves)**

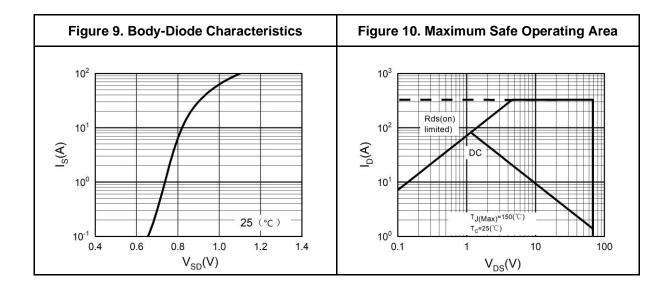






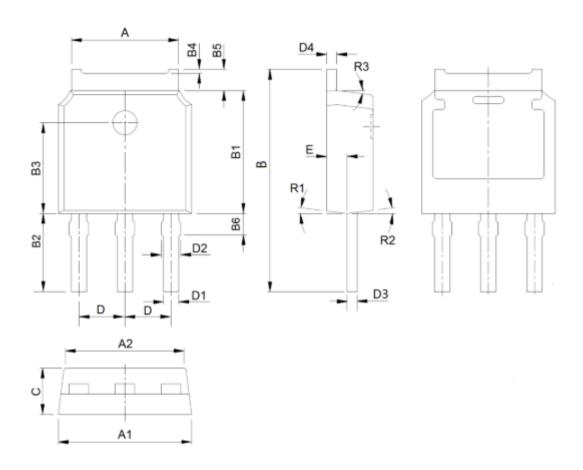
## **Typical Electrical And Thermal Characteristics (Curves)**







# **TO-251 Package Information**



Symbol	Dimensions	Symbol	Dimensions	Symbol	Dimensions	
	(mm)		(mm)		(mm)	
A	$5.3\pm0.2$	B4	0.1 (typ.)	D3	$0.5\pm0.08$	
A1	$6.6\pm0.2$	B5	$0.95\pm0.1$	D4	$0.5\pm 0.08$	
A2	$5.8\pm0.2$	B6	1.2 (typ.)	E	$1.01\pm0.15$	
В	11.05±0.3	C	$2.3\pm0.15$	R1	7° (typ.)	
B1	6.1 $\pm$ 0.2	D	2.286(typ.)	R2	7° (typ.)	
B2	4.0±0.3	D1	$0.76\pm0.1$	R3	7° (typ.)	
В3	$4.5\pm0.15$	D2	$0.91\pm0.1$			

#### Attention

This product described in this document can not be used in life support devices or systems, aircraft's control systems, and other applications whose failure can be reasonably expected to result in serious physical and/or material damage, apart from that when an application agreement is signed between customer and Wuxi Shangjia Semiconductor.

The performances and characteristics of this product in the independent testing state are displayed in this document. Wuxi Shangjia Semiconductor can't guarantee of the performances and characteristics of this described product that mounted in the customer's products or equipments as same as that in the independent testing state. So the customer should evaluate and test devices mounted in the customer's products or equipments.

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